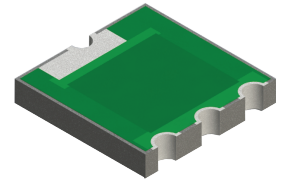


### TZC2525CT-50R0JN-2T-02 Features:

- Solderable Terminals
- RoHS Compliant
- Customer Defined Testing Available
- High Rated Power
- ±5% Resistor Tolerance
- Tape & Reel and Waffle Pack Available (Standard is Bulk)



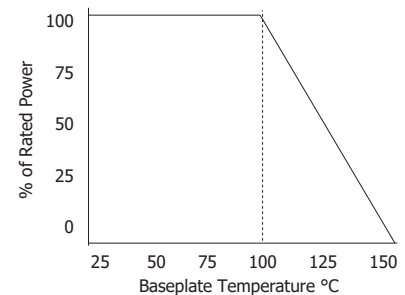
### TZC2525CT-50R0JN-2T-02 Parameters:

Operating Frequency:	DC - 4GHz
Rated Power:	100W*
Return Loss (Typical)**:	20dB or Better (DC - 3GHz) 16dB or Better (>3GHz - 4GHz)
Impedance:	50Ω***
Resistor Construction:	Thick Film on AIN
Terminal Metallization:	100% Matte Tin over Nickel over Silver
Operating Temperature:	-55 to +150°C

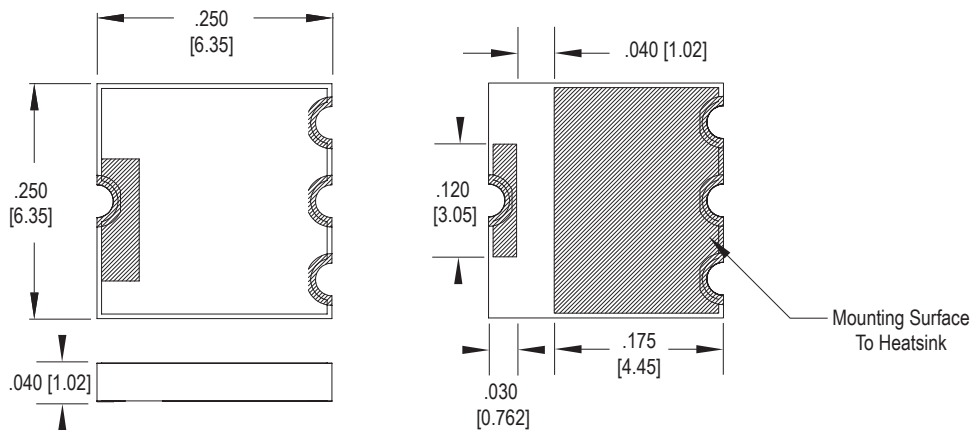


\* Rating based on ≤100°C constant baseplate temperature  
 \*\* In a matched, continuous 50Ω system with proper workmanship  
 \*\*\* Other values and tolerances available. Contact factory.

### TZC2525CT-50R0JN-2T-02 Power Derating Curve



### TZC2525CT-50R0JN-2T-02 Dimensions:



Dimensions in inches [mm]  
 Tolerance is ± 0.010 [0.254]  
 unless otherwise stated

### Ordering Information:

Prefix for Chip Termination w/ Castellations	Size	Impedance Value Code	Tolerance	Normal Inspection	Substrate	Assigned by Factory	Packaging
TZC	2525	50R0	J - 5%	Contact factory for additional options	2T - 0.040" AIN	Factory	Blank - Bulk TR - Tape & Reel WP - Waffle Pack
CT -		RoHS <b>Yes</b>	Magnetic Yes	Solder <b>Yes</b>	Epoxy No	Wirebond No	

Terminal Metallization: CT - Matte Tin over Nickel over Silver

Barry Industries reserves the right to change part number and/or process without notification.



Barry Industries maintains an ISO9001 Certified Quality Management System.

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## TZC2525CT-50R0JN-2T-02 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65°C to +150°C 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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